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(54) **METHOD FOR PREVENTING
ELECTROSTATIC DISCHARGE FAILURE IN
AN INTEGRATED CIRCUIT PACKAGE**

(75) **Inventor:** Ta-Lee Yu, Hsinchu (TW)

(73) **Assignee:** Winbond Electronics Corp., Hsinchu
(TW)

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361/212, 91.5, 91.8, 220; 257/355, 357,
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Primary Examiner—Ronald W. Leja

(74) *Attorney, Agent, or Firm*—Fish & Richardson P.C.

(57) **ABSTRACT**

An integrated circuit package includes a semiconductor chip, bonding pads on the semiconductor chip, a metal lead frame containing electrically with the semiconductor chip, a plurality of wired pins wire-bonded respectively to the bonding pads, and at least one non-wired pin. The non-wired pin is wire-bonded to the metal lead frame to prevent electrostatic discharge failure of the integrated circuit package due to electrostatic discharge stressing of the non-wired pin.

31 Claims, 4 Drawing Sheets

